Form Type	Distribute	**Version**	2.0	**Ref**	IPC 1752A	**Sectionals**	Material Info	**Subsectionals**	D, A

Supplier Information

Company Name	TE Connectivity	**Request Document ID**		**Contact Name**	Kiwi Lee	**Contact Title**	Senior Engineer Product Compliance
Company Unique ID	TE Connectivity	**Response Date**	2014-11-19	**Contact Email**	kiwi.lee@te.com		
Contact Phone Number		886-2-87682788					

Legal Statement

Supplier Acceptance	true

Legal Statement

The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.

Product

Manufacturer Item number	2041119-1	**Amount**	1170.7446	**Version**	-	**Identity**	
Manufacturer Item Name		**Weight Uom**	mg	**Mfr Site**		**Authority**	
Date		**UOM**	Each				

EURoHS-0508	Product(s) meets EU RoHS requirement without any exemptions - true
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products - true
EUREACH-1213	Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH - Not Available / Not Reviewed

Product Disclosure

Sub-Item/Material/Substance	**Level**	**Name**	**Substance Category**	**Substance CAS**	**Substance Concentration**	**Quantity**	**Mass per Unit**	**UOM**	**Exemption**
Material	1	Lower Contact-Au plating				1.0	0.0208	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	1.0	6.24E-5	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0207376	mg	
Material	1	Lower Contact				1.0	85.8	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.085	1.0	0.07293	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.0692406	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	4.86186	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	4.29E-4	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	80.78602	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0069498	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.002574	mg	
Material	1	Solder Pegs-Sn plating				1.0	0.53	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9001	1.0	0.52947	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	5.2947E-4	mg	
Material	1	Solder Pegs				1.0	22.6	mg	
Substance	2	Zinc	Supplier	7440-66-6	35.7546	1.0	8.08054	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0082	1.0	0.0018532	mg	
Substance	2	Copper	Supplier	7440-50-8	64.23	1.0	14.51598	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0015	1.0	3.39E-4	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0057	1.0	0.0012882	mg	
Material	1	Upper Contact				1.0	171.6	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	8.58E-4	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0138996	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.13848	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	161.57204	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	9.72371	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.085	1.0	0.14586	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.005148	mg	

Material	1	Upper Contact-Au plating				1.0	0.0338	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	1.0	1.014E-4	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0336986	mg	
Material	1	Housing				1.0	884.3	mg	
Substance	2	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, [1,1-biphenyl]-4,4-diol and 4-hydroxybenzoic acid	Supplier	60088-52-0	100.0	1.0	884.3	mg	
Material	1	Lower Contact-Ni plating				1.0	1.976	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.4	1.0	0.007904	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	1.96612	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.001976	mg	
Material	1	Solder Pegs-Ni plating				1.0	0.27	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	2.7E-4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.4	1.0	0.00108	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.26865	mg	
Material	1	Upper Contact-Ni plating				1.0	3.614	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	3.59593	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.4	1.0	0.014456	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.003614	mg	